Product Change Notification - KSRA-02RRCB401

Date: 05 Jun 2017

Product Category: Linear Op Amps; Interface- Passive-Keyless-Entry Analog Front End; Touch Controllers; Interface-Infrared Products; Interface- Controller Area Network (CAN); Successive Approximation Register (SAR) A/D Converters; Digital Potentiometers; Linear Comparators; Linear Selectable Gain Amplifiers; Linear Programmable Gain Amplifiers; 8-bit PIC Microcontrollers

Notification subject: CCB 2852: Final Notice: Qualification of CuPdAu bond wire for selected products of 120K wafer technology available in 14L SOIC package at MMT assembly site using 95x155 mils lead frame paddle size

Notification text:

PCN Status:
Final notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products of 120K wafer technology available in 14L SOIC package at MMT assembly site using 95x155 mils lead frame paddle size

Pre Change:
Assembled at MMT using gold (Au) bond wire, 90X110 mils lead frame paddle size, spot LF plating and assembled in MTAI using Palladium coated copper (PdCu) bond wire, 95X155 mils lead frame paddle size, and Bare Cu LF surface

Post Change:
Assembled in MMT using palladium coated copper with gold flash (CuPdAu) bond wire, 95X155 mils lead frame paddle size, and Bare Cu LF surface

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	MMT	MTAI	MMT
Wire material	Au Wire	PdCu Wire	CuPdAu Wire
Die attach material	8390A	8390A	8390A
Molding compound material	G600V	G600V	G600V
Lead frame material	C194	C194	C194
Lead Frame Paddle Size	90x110 mils	95x155 mils	95x155 mils
LF Surface	Spot	Bare Cu	Bare Cu

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at MMT assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
June 12, 2017 (date code: 1724)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2017					-->	May 2017					June 2017			
Workweek	05	06	07	08	09		18	19	20	21	22	23	24	25	26
Initial PCN Issue Date			X												
Qual Report Availability								X							
Final PCN Issue Date								X							
Estimated Implementation Date													X		

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
February 14, 2017: Issued initial notification.
May 09, 2017: Issued final notification. Attached the Qualification Report. Provided estimated first ship date on June 12, 2017
June 05, 2017: Re-issued the final notification to notify all affected customers.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-02RRCB401_Affected CPN.pdf
PCN_KSRA-02RRCB401_Qual Report.pdf
PCN_KSRA-02RRCB401_Affected CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at http://www.microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

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Affected Catalog Part Number (CPN)

PCN_KSRA-02RRCB401
Catalog Part Number
HA1504-I/SL
HA1504T-I/SL
MCP2030A-I/SL
MCP2030AT-I/SL
MCP2030-I/SL
MCP2030T-I/SL
MCP2036-I/SL
MCP2036T-I/SL
MCP2120-I/SL
MCP2120T-I/SL
MCP25020-E/SL
MCP25020-I/SL
MCP25020T-E/SL
MCP25020T-I/SL
MCP25025-I/SL
MCP25025T-I/SL
MCP25050-E/SL
MCP25050-I/SL
MCP25050T-E/SL
MCP25050T-I/SL
MCP25055-I/SL
MCP25055T-I/SL
MCP3004-I/SL
MCP3004T-I/SL
MCP3204-BI/SL
MCP3204-CI/SL
MCP3204T-BI/SL
MCP3204T-CI/SL
MCP3302-BI/SL
MCP3302-CI/SL
MCP3302T-BI/SL
MCP3302T-CI/SL
MCP42010-E/SL
MCP42010-I/SL
MCP42010T-E/SL
MCP42010T-I/SL
MCP42050-E/SL
MCP42050-I/SL
MCP42050T-E/SL
MCP42050T-I/SL
MCP42100-E/SL
MCP42100-I/SL
MCP42100T-E/SL

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Affected Catalog Part Number (CPN)

PCN_KSRA-02RRCB401
Catalog Part Number
MCP42100T-I/SL
MCP6004-E/SL
MCP6004-I/SL
MCP6004-I/SLB21
MCP6004T-E/SL
MCP6004T-I/SL
MCP6004T-I/SLB21
MCP6024-E/SL
MCP6024-I/SL
MCP6024T-E/SL
MCP6024T-I/SL
MCP6044-E/SL
MCP6044-E/SLBAA
MCP6044-I/SL
MCP6044T-E/SL
MCP6044T-E/SLBAA
MCP6044T-I/SL
MCP604-E/SL
MCP604-I/SL
MCP604T-E/SL
MCP604T-I/SL
MCP609-I/SL
MCP609T-I/SL
MCP6144-E/SL
MCP6144-I/SL
MCP6144T-E/SL
MCP6144T-I/SL
MCP619-I/SL
MCP619-I/SLB21
MCP619T-I/SL
MCP619T-I/SLB21
MCP6234-E/SL
MCP6234T-E/SL
MCP6244-E/SL
MCP6244T-E/SL
MCP6274-E/SL
MCP6274-E/SLB21
MCP6274T-E/SL
MCP6274T-E/SLB21
MCP6284-E/SL
MCP6284-E/SLDAA
MCP6284T-E/SL
MCP6284T-E/SLDAA

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Affected Catalog Part Number (CPN)

PCN_KSRA-02RRCB401
Catalog Part Number
MCP6294-E/SL
MCP6294T-E/SL
MCP6404-E/SL
MCP6404-H/SL
MCP6404T-E/SL
MCP6404T-H/SL
MCP6409-H/SL
MCP6409T-H/SL
MCP6444-E/SL
MCP6444T-E/SL
MCP6544-E/SL
MCP6544-I/SL
MCP6544T-E/SL
MCP6544T-I/SL
MCP6549-E/SL
MCP6549-I/SL
MCP6549T-E/SL
MCP6549T-I/SL
MCP6G04-E/SL
MCP6G04T-E/SL
MCP6L04T-E/SL
MCP6L4T-E/SL
MCP6L74T-E/SL
MCP6L94T-E/SL
MCP6S26-I/SL
MCP6S26T-I/SL
PIC16C505-04/SL
PIC16C505-04/SLC01
PIC16C505-04E/SL
PIC16C505-04I/SL
PIC16C505-20/SL
PIC16C505-20E/SL
PIC16C505-20I/SL
PIC16C505T-04/SL
PIC16C505T-04/SL098
PIC16C505T-04E/SL
PIC16C505T-04E/SL115
PIC16C505T-04I/SL
PIC16C505T-04I/SL060
PIC16C505T-04I/SL111
PIC16C505T-04I/SL137
PIC16C505T-20/SL
PIC16C505T-20E/SL

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Affected Catalog Part Number (CPN)

PCN_KSRA-02RRCB401
Catalog Part Number
PIC16C505T-20I/SL
PIC16LC505-04/SL
PIC16LC505-04I/SL
PIC16LC505T-04/SL
PIC16LC505T-04I/SL